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PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A process for producing a semiconductor device, comprising the steps of providing a wafer having a surface with semiconductor circuits and a back; forming grooves of a depth smaller than the thickness of the wafer on the wafer circuit surface; sticking a surface protective sheet onto the wafer circuit surface; grinding the back of the wafer to cause division of the wafer into individual chips with spaces therebetween; sticking a dicing/die bond sheet having a base with an adhesive layer onto the back of the wafer, such that said adhesive layer is in contact with the back of the wafer; peeling the surface protective sheet from the wafer circuit surface to expose the adhesive layer through the spaces between individual chips; cutting the exposed adhesive layer; detaching the individual chips having the cut adhesive layer adhering thereto; and bonding the individual chips through the adhesive layer to a given substrate.

Figure 5



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